

**REMARKS**

*Claim Rejections Under 35 U.S.C. § 103*

Claims 1-4 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Beerling et al. (U.S. Patent No. 6,508,536). Applicant respectfully traverses.

Claim 1 includes providing a mold for dispensing an encapsulant on top of an electrical coupling to form a substantially co-planar surface with the fluid ejecting substrate and an upper surface of the carrier. Beerling et al. does not include or suggest this. The Examiner has taken the carrier substrate 20 of Figure 10 as corresponding to the carrier of claim 1, the printhead die 18 (18') as corresponding to the fluid ejecting substrate of claim 1, and encapsulant 124 as corresponding to the encapsulant of claim 1. Figure 10 shows that carrier substrate 20 has an upper surface 70 that lies in a different plane than either the surface 58 or surface 60 (see Figure 5) of printhead die 18 (18'). Figure 10 further shows that encapsulant 124 does not have a substantially co-planar surface with upper surface 70 and either the surface 58 or the surface 60. Moreover, the configuration of Figure 10 would have to be altered in order for encapsulant 124 to have a substantially co-planar surface with upper surface 70 and either the surface 58 or the surface 60. Therefore, Applicant contends that it would not be obvious to alter Beerling et al. so that a mold can be used for dispensing an encapsulant to form a substantially co-planar surface with the fluid ejecting substrate and an upper surface of the carrier. Thus, Beerling et al. does not include or suggest each and every recitation of claim 1, so claim 1 should be allowed.

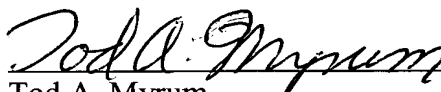
Claims 2-4 depend from claim 1 and thus are allowable for at least the same reasons as claim 1. Therefore, claims 2-4 should be allowed.

**CONCLUSION**

In view of the above remarks, Applicant believes that the claims are in condition for allowance and respectfully requests a Notice of Allowance be issued in this case. If the Examiner has any questions regarding this application, please contact the undersigned at (612) 312-2208.

Respectfully submitted,

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